

SPECIFICATIONS

Optical & Imaging System

Camera Type	4 MP camera	
Optical Resolution	10 µm or 15 µm (factory setting)	
Field of View	10 µm	20.0 x 20.0 mm (0.79 x 0.79 in)
	15 µm	30.0 x 30.0 mm (1.18 x 1.18 in)

Inspection Functions

Defects Detected	Insufficient Paste, Excessive Paste, Shape Deformity, Missing Paste & Bridging
Measurement	Height, area, volume and offset

Mechanical Stage

X-axis linear motor and linear scale with DSP-based motion controller	
XY Resolution	0.5 µm
Z Resolution	1 µm

Inspection Speed

10 µm	Up to 90 cm ² /sec (14.0 in ² /sec)
15 µm	Up to 200 cm ² /sec (31.0 in ² /sec)

Inspection Performance

Volume Repeatability	
Calibration Target (at 3 σ)	<1% on TRI certification target
Height Repeatability	
Calibration Target (at 3 σ)	<1% on TRI certification target
Solder GR&R (± 50% Tolerance)	<<10% at 6 σ

Effective Depth of Focus	± 5 mm (± 0.10 in)	
Height Resolution	0.4 µm	
Height Accuracy	1.5 µm on certification target	
Max. Solder Paste Size	12800 x 10240 µm at 10 µm	
Min. Solder Paste Size	100 x 100 µm at 10 µm	
Min. Solder Paste Pitch	100 µm	
Max. Height Range	10 µm	600 µm
	15 µm	550 µm



PCB and Conveyor System

	TR7007M SII Plus	TR7007 SII Plus
PCB Size	50 x 50 - 350 x 350 mm (1.97 x 1.97 - 13.8 x 13.8 in)	50 x 50 - 510 x 460 mm (1.97 x 1.97 - 20.1 x 18.1 in)
PCB Thickness	0.6 - 6 mm	
PCB Transport Height	880 - 920 mm	
Max. PCB Weight	3 kg (6.61 lbs)	
PCB Carrier/Fixing	Belt/Pneumatic	
Clearance	Top	40 mm
	Bottom	40 mm
	Edge	3 mm

Dimensions

	TR7007M SII Plus	TR7007 SII Plus
Dimensions (W x D x H)	1000 x 1555 x 1500 mm (39.4 x 61.2 x 59.1 in) (not including signal tower, height: 520 mm)	1100 x 1570 x 1550 mm (43.3 x 61.8 x 61.0 in) (not including signal tower, height: 520 mm)
Weight	870 kg (1918 lbs)	950 kg (2094 lbs)
Power Requirement	200 - 240 V, single phase, 50/60 Hz 3 kVA	
Air Requirement	0.6 MPa (87 psi)	

Optional

SPC, Offline Editor, Gerber Tool, Barcode Scanner (linear & 2D) and Support Pins, Closed Loop Function, Dual Lane, Y-Axis Linear Motor, TRI's Yield Management System (YMS), YMS Lite, Auto Conveyor Width Adjustment

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Test Research, Inc.

Headquarters

7F., No.45, Dexing West Rd.,
Shilin Dist., Taipei City
11158, Taiwan
TEL: +886-2-2832-8918
FAX: +886-2-2831-0567
E-Mail: sales@tri.com.tw
http://www.tri.com.tw

Linkou, Taiwan

No.256, Huaya 2nd Rd.,
Guishan Shiang, Taoyuan
County 33383, Taiwan
TEL: +886-2-2832-8918
FAX: +886-3-328-6579

Hsinchu, Taiwan

7F., No.47, Guangming 6th
Rd., Zhubei City, Hsinchu
County 30268, Taiwan
TEL: +886-2-2832-8918
FAX: +886-3-553-9786

Shenzhen, China

5F.3, Guangxia Rd., Shang-mei-lin
Area, Fu-Tian District, Shenzhen,
Guangdong, 518049, China
TEL: +86-755-83112668
FAX: +86-755-83108177
E-mail: shenzhen@cn.tri.com.tw

Suzhou, China

B Unit, Building 4, 78 Xinglin
St., Suzhou Industrial Park,
215123, China
TEL: +86-512-68250001
FAX: +86-512-68096639
E-mail: suzhou@cn.tri.com.tw

Shanghai, China

Room 6C, 6F, Building 14,
470 Guiping Rd., Xuhui Dist.,
Shanghai, 200233, China
TEL: +86-21-54270101
FAX: +86-21-64957923
E-mail: shanghai@cn.tri.com.tw

USA

1923 Hartog Drive
San Jose, CA 95131 U.S.A
TEL: +1-408-567-9898
FAX: +1-408-567-9288
E-mail: triusa@tri.com.tw

Europe

O'Brien Strasse 14
91126 Schwabach
Germany
TEL: +49-9122-631-2127
FAX: +49-9122-631-2147
E-mail: trieuropa@tri.com.tw

Japan

2-9-9 Midori, Sumida-ku,
Tokyo, 130-0021 Japan
TEL: +81-3-6273-0518
FAX: +81-3-6273-0519
E-mail: trijp@tri.com.tw

Korea

No.207 Daewoo-Technopia,
768-1 Wonsi-Dong, Danwon-Gu,
Ansan City, Gyeonggi-Do, Korea
TEL: +82-31-470-8858
FAX: +82-31-470-8859
E-mail: trikri@tri.com.tw

Malaysia

C11-1, Ground Floor, Lorong
Bayan Indah 3 Bay Avenue,
11900 Bayan Lepas Penang,
Malaysia
TEL: +604-6461171
E-mail: trimy@tri.com.tw

C-7007 SII PLUS-EN-1402



TR7007 SII Plus SERIES



3D SOLDER
PASTE INSPECTION

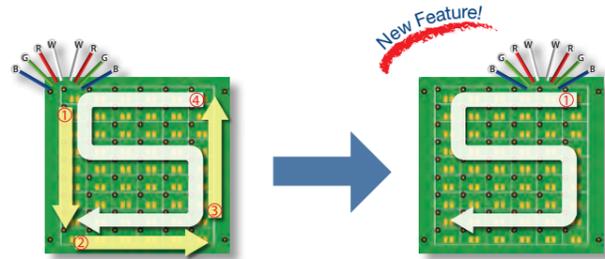
TR7007 SII Plus FEATURES

TR7007 SII Plus

Highly Accurate shadow-free SPI solution with class-leading inspection performance and easy programming brings maximum value to your production line.

Unmatched Speed & Throughput

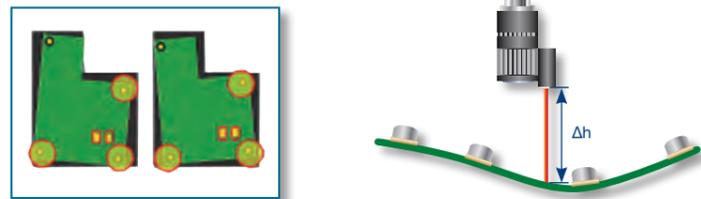
Industry-leading inspection speed using TRI's Dynamic Imaging technology keeps up with the production line beat without slowing down for even the most complex boards with multiple local fiducial marks. TRI's unique solution guarantees perfect results while reducing expensive cycle time.



TRI's Color Imaging needs to scan only one Fiducial Mark on every board, saving cycle time.

Stable and Reliable Performance

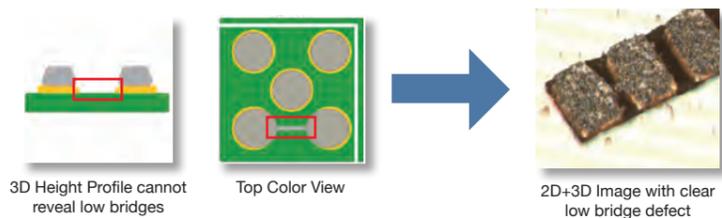
Fully optimized for maximum stability, the TR7007 SII Plus delivers reliable inspection results 24 hours a day, and automatically compensates for manufacturing tolerances and board warp.



Reliable warp compensation and local fiducial marks guarantee stable results under any conditions.

Unique Low Bridge Inspection

World's first inspection of low solder paste bridges under 30 μm ensures no printing defects are missed, and guarantees accurate results under any conditions.



Intuitive SPC Display

Full panel maps and real color images allow engineers to quickly monitor and diagnose problematic areas on the stencil, saving management time and reducing rework costs.

SPC

Statistical Report

Multi-panel Histogram

Solder Height Distribution

3D Color Image

SPC 2D Real Image Query

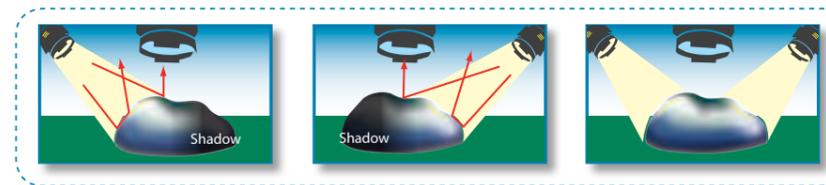
Easy Automated Programming

Rapid automated 5-step programming interface ensures fast changeovers, minimal idle time and helps reduce operator work load.



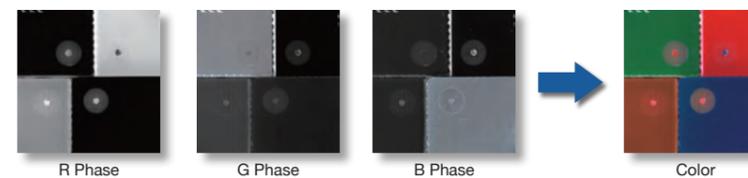
Shadow Free Inspection Technology

Dual projection design and intelligent software ensure the TR7007 SII Plus delivers completely shadow-free inspection results and eliminates problems with specular reflections.



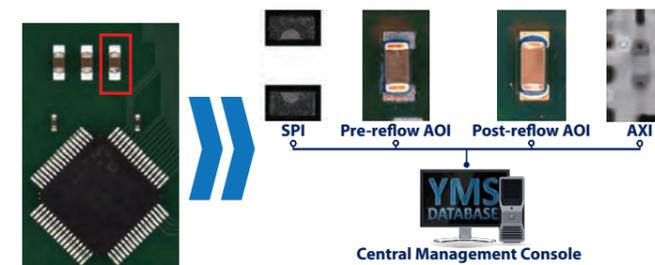
Multi-Color Vision for any PCB

Multi-phase color lighting guarantees accurate inspection results on any PCB color and finish combination, without sacrificing inspection speed.



SMT Line Integration

TRI's Yield Management System links inspection data from SPI, AOI and AXI systems to trace defect roots throughout the PCB assembly line. Modular architecture provides centralized inspection management, real time defect monitoring with analysis and knowledge management necessary to identify problems and implement solutions to maximize production yields.



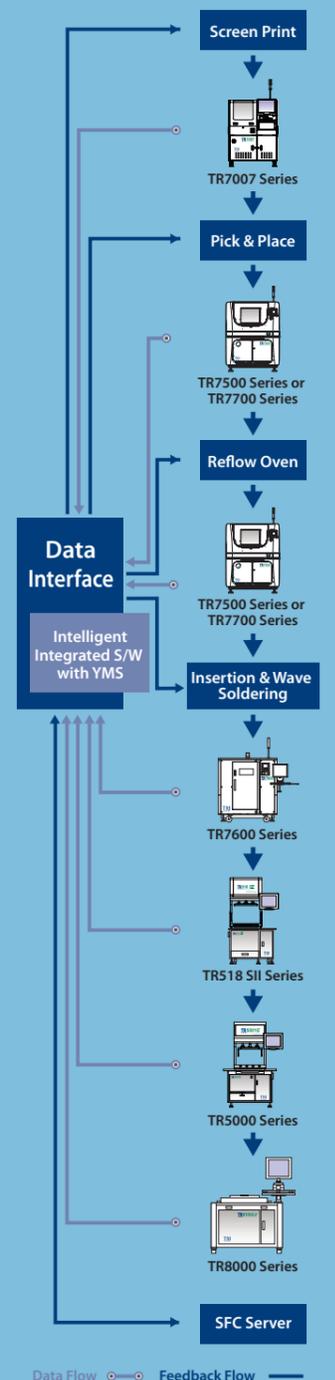
Closed Loop Function

TRI SPI systems share inspection results with connected SMT line equipment to help improve production yields and stabilize production quality while minimizing line stops and reducing production costs.

High Production Value = Maximum Cost Savings

- Industry Leading Inspection Speed
- Early Defect Detection
- 98% Rework Cost Reduction
- Stable and Reliable Results
- Enhanced 100% Defect Coverage

Yield Management System*



- Inspection results and data integration
- Real time SPC and production yield management
- Quality reports and close loop tracking
- Support defect component analysis and improvements
- Knowledge Management (KM)
- Productivity and Quality Management

* Optional